

# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V <sub>DSS</sub>	20	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	V
Drain Current (Note 5)	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	8 6.7	А
Pulsed Drain Current (Note 6)			I <sub>DM</sub>	30	Α

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P <sub>D</sub>	1.3	W
Thermal Resistance, Junction to Ambient	R <sub>0JA</sub>	96	°C/W
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-55 to +150	°C

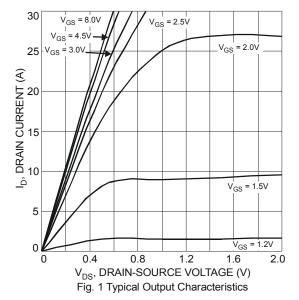
### **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

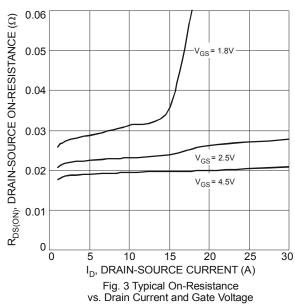
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	V	$V_{GS} = 0V$ , $I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS	_	_	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5	_	0.9	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
			19	24		$V_{GS} = 4.5V, I_D = 8.2A$	
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>	<u> </u>	23	29	mΩ	$V_{GS} = 2.5V, I_D = 3.3A$	
			29	37		$V_{GS} = 1.8V, I_D = 2A$	
Forward Transfer Admittance	Y <sub>fs</sub>	_	7	_	S	$V_{DS} = 10V, I_D = 4A$	
Diode Forward Voltage	$V_{SD}$	0.5	_	0.9	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C <sub>iss</sub>	_	867	_	pF	151/1/	
Output Capacitance	Coss	_	85	_	pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V -f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	81	_	pF		
Gate Resistance	R <sub>G</sub>	_	1.29	_	Ω	$V_{GS} = 0V$ , $V_{DS} = 0V$ , $f = 1MHz$	
SWITCHING CHARACTERISTICS (Note 8)							
Total Gate Charge	$Q_g$	_	8.8	_	nC	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 8.2A	
Gate-Source Charge	$Q_{gs}$	_	1.2	_	nC		
Gate-Drain Charge	$Q_{gd}$	_	3	_	nC		
Turn-On Delay Time	t <sub>d(on)</sub>	_	13.2	_	ns	$V_{DD}$ = 10V, $V_{GS}$ = 4.5V, $R_{L}$ = 10 $\Omega$ , $R_{G}$ = 6 $\Omega$	
Turn-On Rise Time	t <sub>r</sub>	_	12.6	_	ns		
Turn-Off Delay Time	t <sub>d(off)</sub>	_	64.8		ns		
Turn-Off Fall Time	t <sub>f</sub>	_	21.7	_	ns		

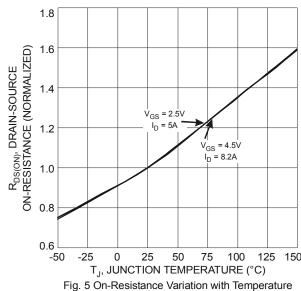
Notes:

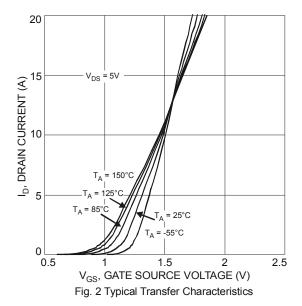
- 5. Device mounted on FR-4 PCB with minimum recommended pad layout.
- 6. Repetitive rating, pulse width limited by function temperature.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.











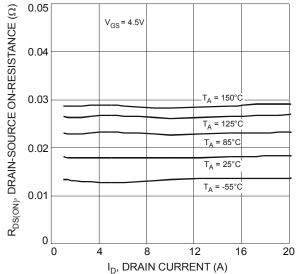


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

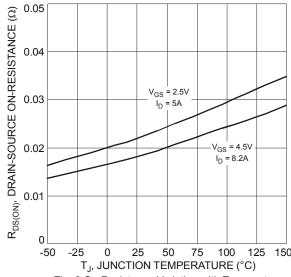


Fig. 6 On-Resistance Variation with Temperature

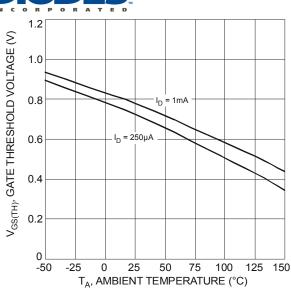
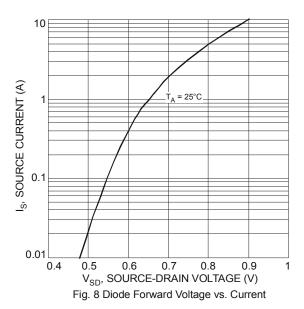
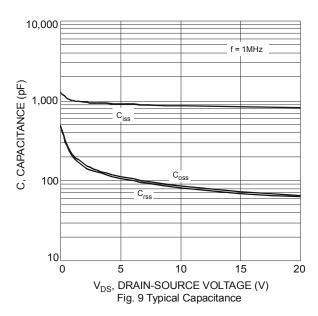
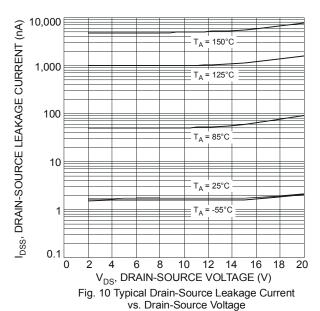


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







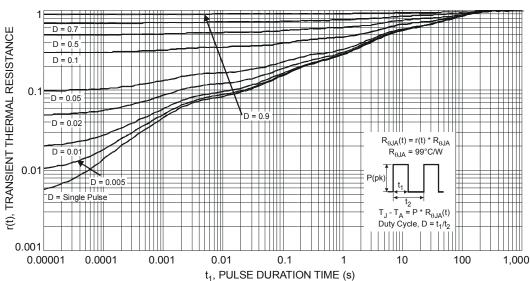
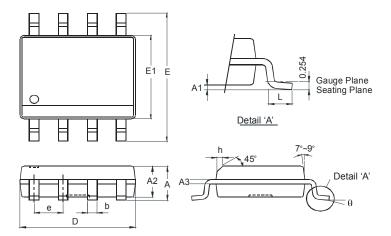


Fig. 11 Transient Thermal Response



## **Package Outline Dimensions**

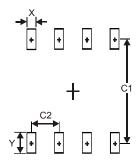
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOP-8L				
Dim	Min	Max		
Α	-	1.75		
A1	0.10	0.20		
A2	1.30	1.50		
A3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
Е	5.90	6.10		
E1	3.85	3.95		
е	1.27 Typ			
h	-	0.35		
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
X	0.60
Υ	1.55
C1	5.4
C2	1.27



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